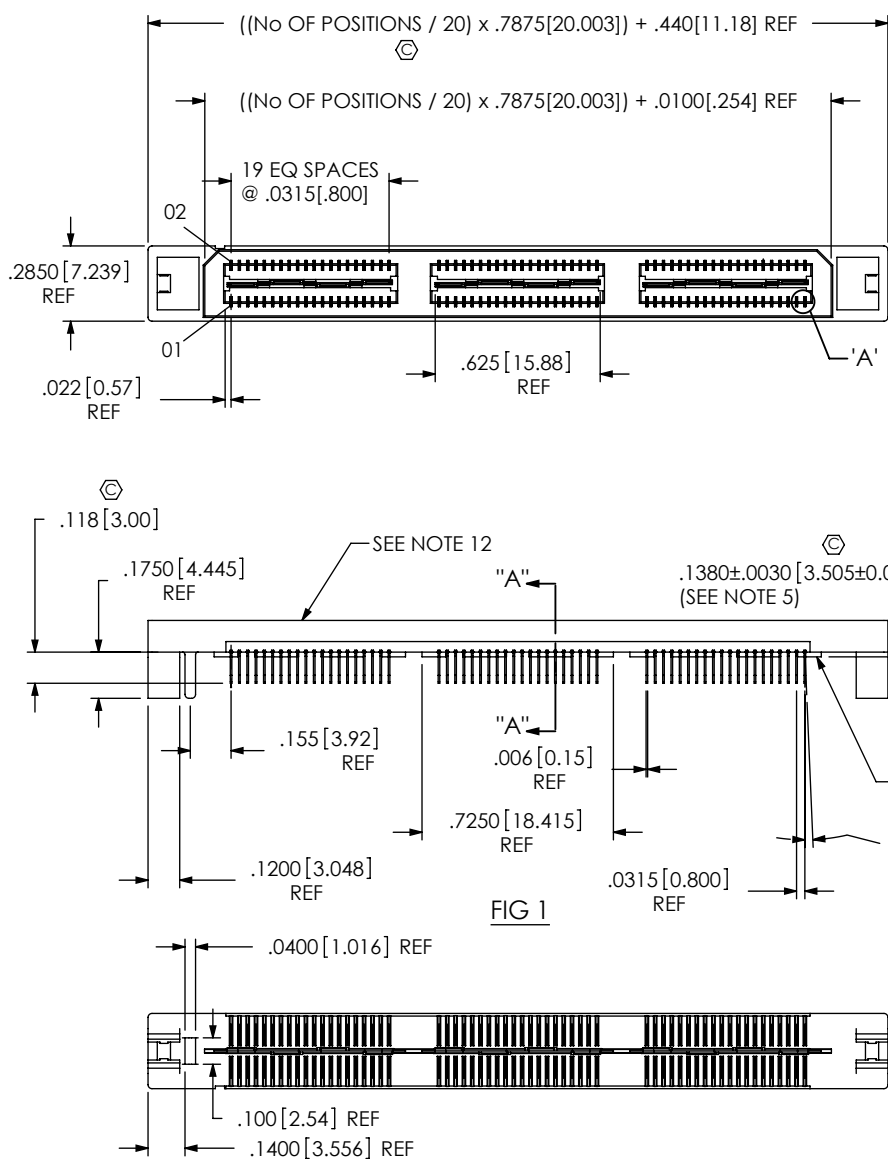


DO NOT SCALE FROM THIS PRINT



QSE-XXX-01-X-D-EMX-XX

No OF POSITIONS
 -020, -040, -060
 **080 **100
 (PER ROW)

LEAD STYLE
 -01: .1380 [3.505]

PLATING SPECIFICATION

PLATING THICKNESSES ARE FOR SIGNAL PINS ONLY. FOR GROUND PLANE THICKNESSES, SEE PP-T-1G13-XX-X.

-F: 3μ" FLASH SELECTIVE GOLD IN CONTACT AREA MATTE TIN ON TAIL (SEE NOTE 6) (USE C-162-XX-F & T-1G13-01-F)

-L: 10μ" LIGHT SELECTIVE GOLD IN CONTACT AREA WITH MATTE TIN ON TAIL (USE C-162-XX-L & T-1G13-01-L)

-H: 30μ" HEAVY GOLD IN CONTACT AREA 3μ" FLASH GOLD ON TAILS (USE C-162-XX-H & T-1G13-01-G)

-TL: TIN/LEAD (90/10±5%) CONTACT AND TAIL

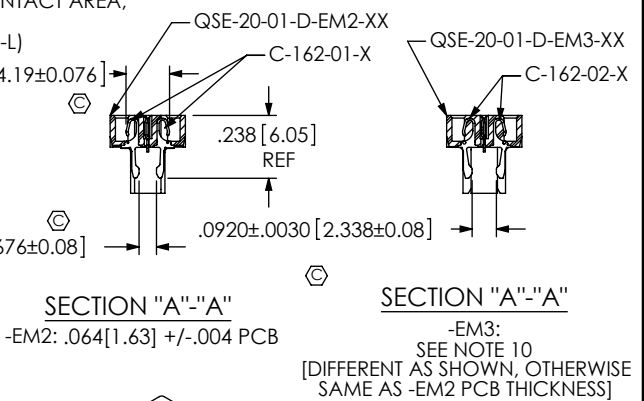
-S: 30μ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL (USE C-162-XX-S & T-1G13-01-L)

OPTION
 * -GP: GUIDE POST (60 POS MAX) (SEE FIG 2, SEE SHEET 2)
 -TY: TRAY PACKAGING
 * EM3-GP = NOT TOOLED

EDGE MOUNT THICKNESS
 -EM2: .064[1.63] +/- .004 PCB (USE QSE-20-01-D-EM2-XX & C-162-01-X)
 -EM3: (USE QSE-20-01-D-EM3-XX & C-162-02-X) (SEE NOTE 10)

ROW SPECIFICATION
 -D: DOUBLE (USE QSE-20-01-D-EMX-XX)

No OF BANKS
 * = SEE NOTE 10
 ** = SEE NOTE 13



- NOTES:
1. Ⓢ REPRESENTS A CRITICAL DIMENSION.
 2. MINIMUM CONTACT RETENTION: 6 OZ
 3. MINIMUM GROUND PLANE RETENTION: 8 OZ
 4. PARTS ARE MOLD TO POSITION.
 5. MAXIMUM VARIANCE OF .002[0.05]
 6. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING.
 7. NOTE DELETED.
 8. BOARD THICKNESS TO BE MEASURED FROM SOLDER PAD TO SOLDER PAD.
 9. SEE WWW.SAMTEC.COM/PROCESSING/EDGEMOUNT_TECTALK/INDEX.HTM FOR INFORMATION ON PROCESSING EDGEMOUNT PARTS TO BOARDS.
 10. -EM3 IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY. PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP WITH ORDER INQUIRIES
 11. NOTE DELETED.
 12. SIDE WALLS ARE RIBBED AS NECESSARY TO CONTROL BOW.
 13. AVAILABLE FOR EXISTING CUSTOMERS ONLY.

TABLE 1

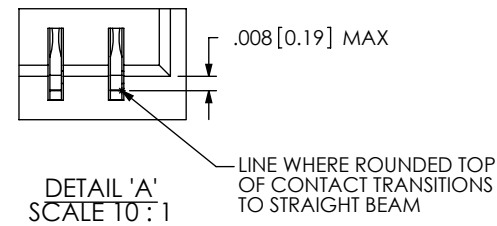
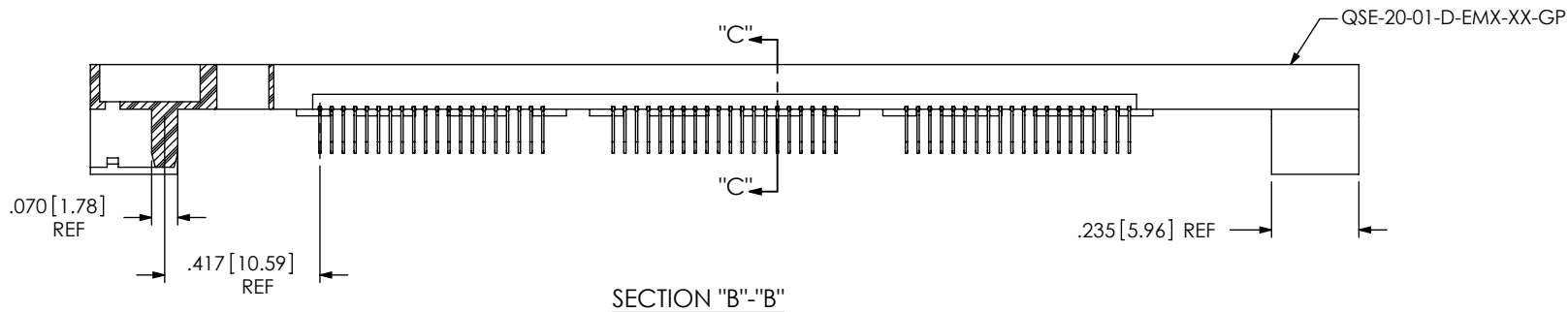
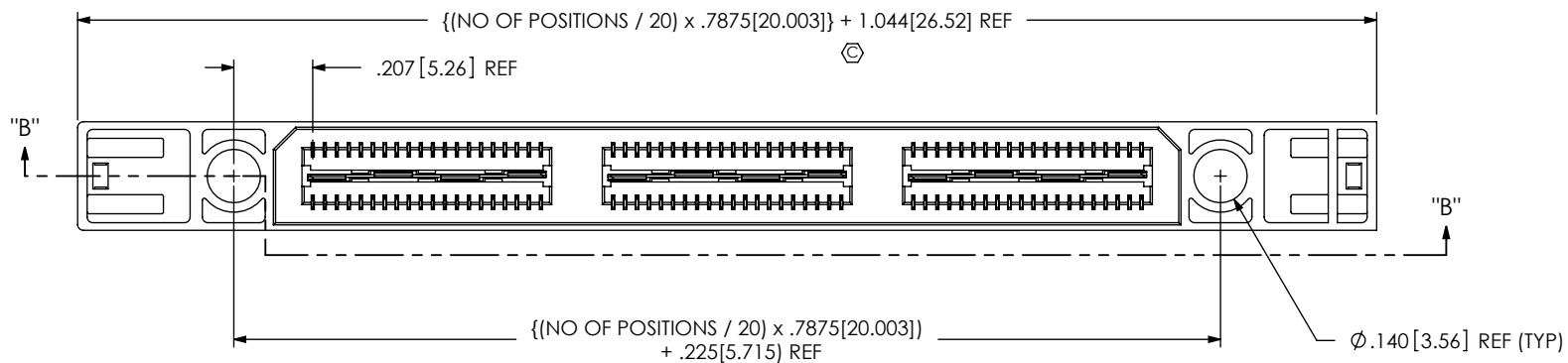
No OF POSITIONS	GND PLANE COPLANARITY	ASSEMBLY BOW
-020 THRU -060	.004 [0.10]	.004 [0.10]
**080 THRU **100	.005[1.27]	.006[0.15]

** = SEE NOTE 13

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES. TOLERANCES ARE: DECIMALS ANGLES .XX: ±.01[.3] .XXX: ±.005[.13] .XXXX: ±.0020[.051]	PROPRIETARY NOTE THIS DOCUMENT CONTAINS INFORMATION CONFIDENTIAL AND PROPRIETARY TO SAMTEC, INC. AND SHALL NOT BE REPRODUCED OR TRANSFERRED TO OTHER DOCUMENTS OR DISCLOSED TO OTHERS OR USED FOR ANY PURPOSE OTHER THAN THAT WHICH IT WAS OBTAINED WITHOUT THE EXPRESSED WRITTEN CONSENT OF SAMTEC, INC.		
		520 PARK EAST BLVD. NEW ALBANY, IN 47150 PHONE: 812-944-6733 FAX: 812-948-5047 e-Mail: info@SAMTEC.com code 55322	
MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 1:375:		DESCRIPTION: .8mm EDGE MOUNT HS SOCKET ASSEMBLY	
INSULATOR: LCP, UL 94V0 -EM2 COLOR: BLACK -EM3 COLOR: NATURAL CONTACT & GROUND PLANE: PHOS BRONZE		DWG. NO. QSE-XXX-01-X-D-EMX-XX	
F:\DWG\MISC\MKTG\QSE-XXX-01-X-D-EMX-XX-MKT.SLDDRW		BY: DEAN P 5/24/2000	SHEET 1 OF 2

FIG 2

-GP: GUIDE POST
 (DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)
 (60 POSITION MAX)
 (ONLY AVAILABLE WITH -EM2 OPTION)



CRITICAL DIMENSION INSPECTION INSTRUCTION TABLE	
ASSEMBLY OPERATION	IN-PROCESS INSPECTION
FILL C-162-XX-X	C1, C2, C4*, C5*, C7, C8
FILL T-1G13-01-X	C6
WHERE APPLICABLE *	

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DO NOT SCALE DRAWING
 SHEET SCALE: 2:1



520 PARK EAST BLVD., NEW ALBANY, IN 47150
 PHONE: 812-944-6733 FAX: 812-948-5047
 e-Mail info@SAMTEC.com code 55322

DESCRIPTION:
 .8mm EDGE MOUNT HS SOCKET ASSEMBLY

DWG. NO.
QSE-XXX-01-X-D-EMX-XX

BY: DEAN P 5/24/2000 SHEET 2 OF 2

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